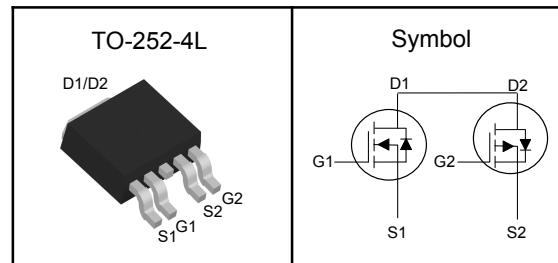


Dual N+P Channel Enhancement Mode MOSFET

Features

- Low $R_{DS(on)}$ for low conduction loss
- Reliable and Rugged
- ROHS Compliant & Halogen-Free

Pin Description



Applications

- Power Management in Desktop Computer
- DC/DC Converters

V_{DSS}	40	-40	V
$R_{DS(ON)-Typ}$	14	32	$\text{m}\Omega$
I_D	28	-25	A

Absolute Maximum Ratings ($T_C=25^\circ\text{C}$, Unless Otherwise Noted)

Symbol	Parameter	N-Channel	P-Channel	Unit
V_{DSS}	Drain-Source Voltage	40	-40	V
V_{GSS}	Gate-Source Voltage	± 20	± 20	V
T_J	Maximum Junction Temperature	-55 to 150	-55 to 150	$^\circ\text{C}$
T_{STG}	Storage Temperature Range	-55 to 150	-55 to 150	$^\circ\text{C}$
$I_{DM}^{①}$	Pulse Drain Current Tested	80	-80	A
I_D	Continuous Drain Current	28	-25	A
P_D	Maximum Power Dissipation	32.9	32.9	W
E_{AS}	Single Pulse Avalanche Energy	25	25	mJ
I_{AS}	Avalanche Current	10	-10	A

Thermal Characteristics

Symbol	Parameter	Rating	Unit
$R_{\theta JA}^{③}$	Thermal Resistance-Junction to Ambient	62	$^\circ\text{C}/\text{W}$
$R_{\theta JC}$	Thermal Resistance Junction-Case	5.0	$^\circ\text{C}/\text{W}$

Note ① : Max. current is limited by bonding wire.

Note ② : UIS tested and pulse width are limited by maximum junction temperature 150°C .

Note ③ : Surface Mounted on 1in² FR-4 board with 1oz.

Dual N+P Channel Enhancement Mode MOSFET
Electrical Characteristics (T_J=25°C, Unless Otherwise Noted)

Symbol	Parameter	Test Conditions	Min	Typ	Max	Unit
Static Electrical Characteristics						
BV _{DSS}	Drain-Source Breakdown Voltage	V _{GS} =0V, I _D =250μA	40	---	---	V
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} =32V, V _{GS} =0V	---	---	1	μA
V _{GS(th)}	Gate Threshold Voltage	V _{DS} =V _{GS} , I _D =250μA	1.5	---	2.5	V
I _{GSS}	Gate Leakage Current	V _{GS} =±20V, V _{DS} =0V	---	---	±100	nA
R _{DS(ON)}	Drain-Source On-state Resistance	V _{GS} =10V, I _D =10A	---	14	21	mΩ
		V _{GS} =4.5V, I _D =5A	---	18	25	
g _f s	Forward Transconductance	V _{DS} =5V, I _D =5A	---	14	---	S
Dynamic Characteristics^⑤						
C _{iss}	Input Capacitance	V _{GS} =0V, V _{DS} =20V, Freq.=1MHz	---	815	---	pF
C _{oss}	Output Capacitance		---	95	---	
C _{rss}	Reverse Transfer Capacitance		---	60	---	
T _{d(on)}	Turn-on Delay Time	V _{DD} =20V, V _{GS} =10V, R _G =6Ω, I _D =1A	---	7.8	---	nS
T _r	Turn-on Rise Time		---	6.9	---	
T _{d(off)}	Turn-off Delay Time		---	22.4	---	
T _f	Turn-off Fall Time		---	4.8	---	
Q _g	Total Gate Charge(4.5V)	V _{DS} =20V, V _{GS} =10V, I _D =10A	---	15.7	---	nC
Q _{gs}	Gate-Source Charge		---	3.24	---	
Q _{gd}	Gate-Drain Charge		---	2.75	---	
Source-Drain Characteristics						
V _{SD} ^④	Diode Forward Voltage	V _{GS} =0V, I _S =1A, T _J =25°C	---	---	1.1	V
I _S	Continuous Source Current	V _G =V _D =0V, Force Current	---	---	6.1	A
I _{SM}	Pulsed Source Current		---	---	23	A

Note ④: Pulse test (pulse width 300us, duty cycle 2%).

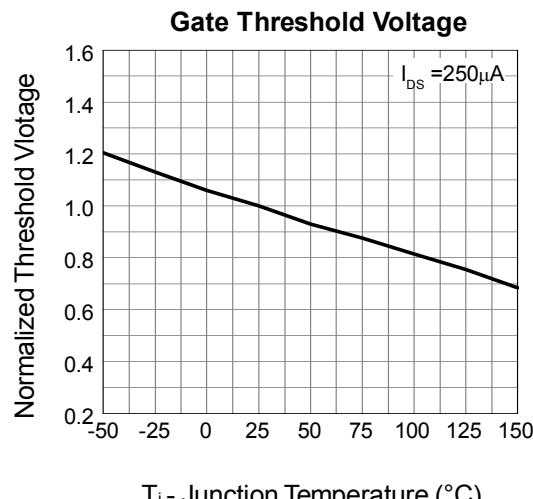
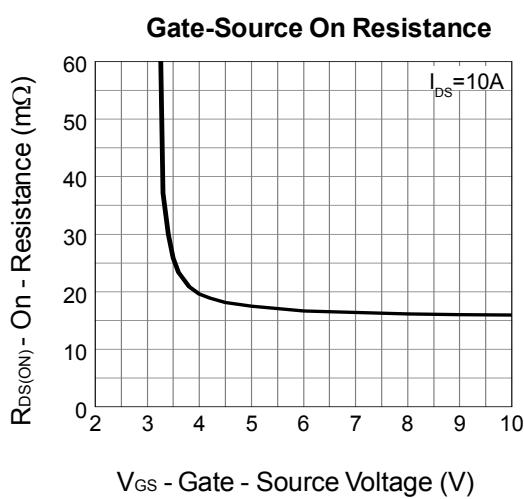
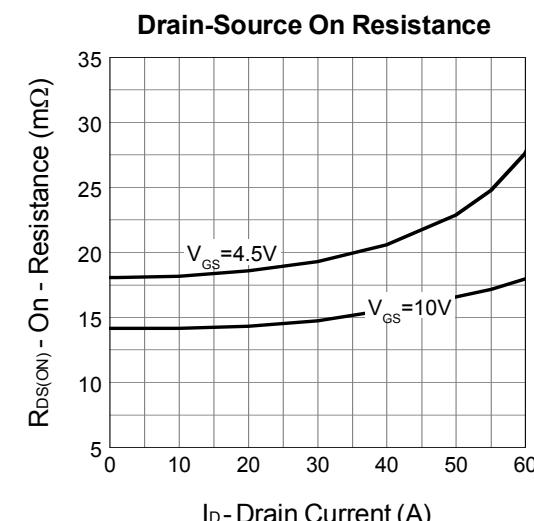
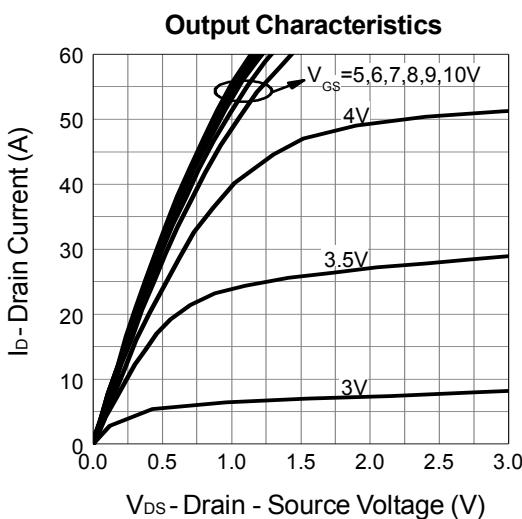
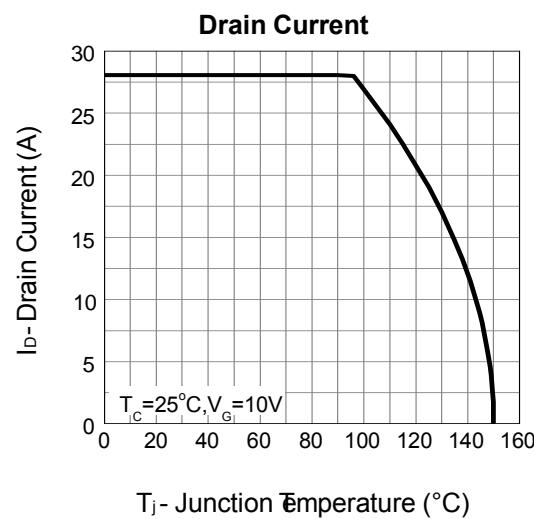
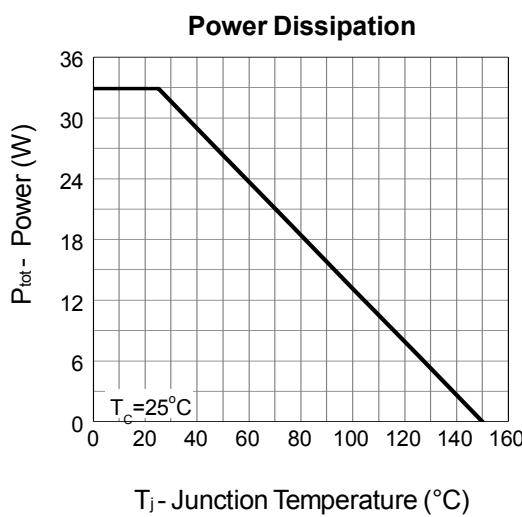
Note ⑤ : Guaranteed by design, not subject to production testing.

Dual N+P Channel Enhancement Mode MOSFET
Electrical Characteristics (T_J=25°C, Unless Otherwise Noted)

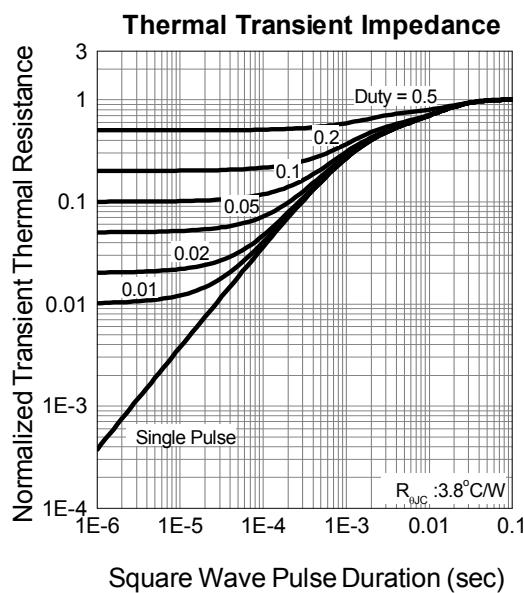
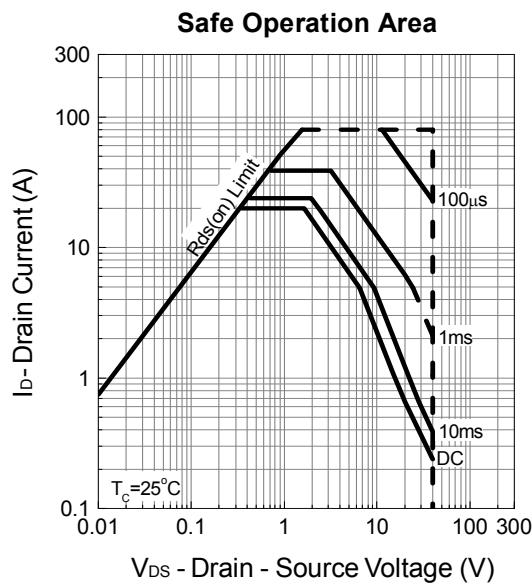
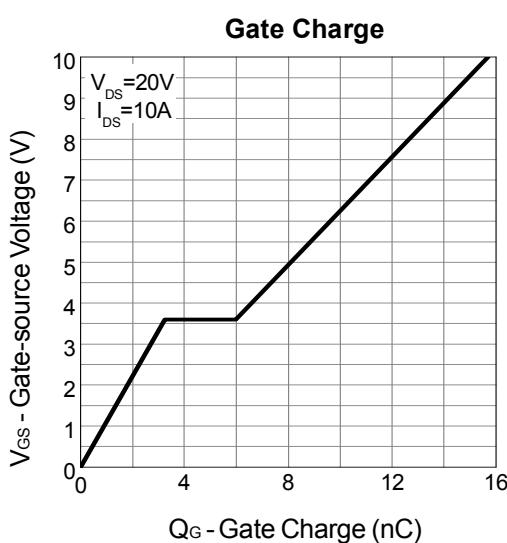
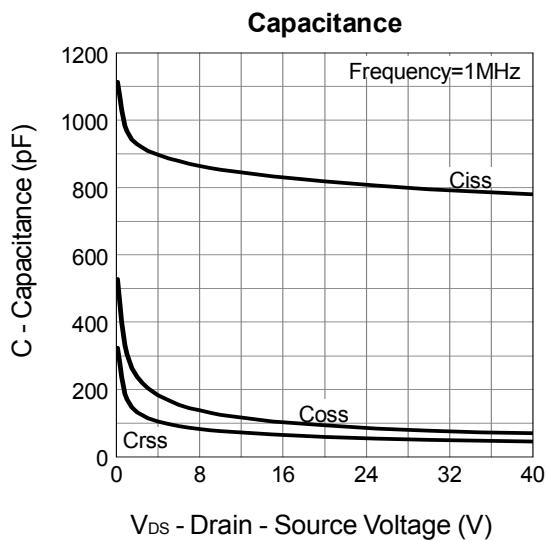
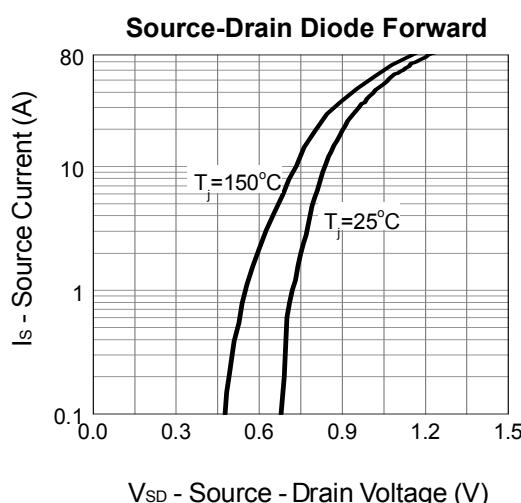
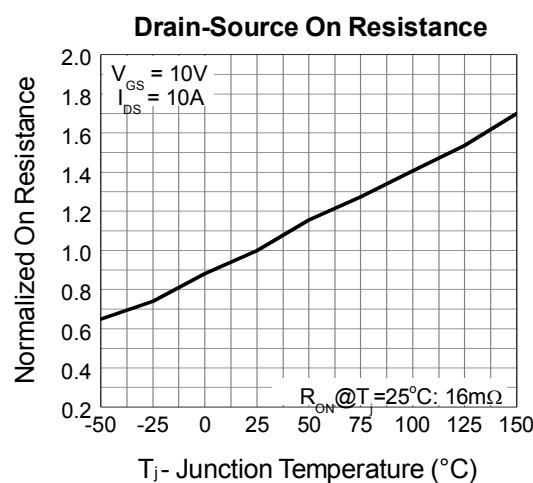
Symbol	Parameter	Test Conditions	Min	Typ	Max	Unit
Static Electrical Characteristics						
BV _{DSS}	Drain-Source Breakdown Voltage	V _{GS} =0V, I _D =-250μA	-40	---	---	V
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} =-32V, V _{GS} =0V	---	---	1	uA
V _{GS(th)}	Gate Threshold Voltage	V _{DS} =V _{GS} , I _D =-250μA	-1.5	---	-2.5	V
I _{GSS}	Gate Leakage Current	V _{GS} =±20V, V _{DS} =0V	---	---	±100	nA
R _{DS(ON)}	Drain-Source On-state Resistance	V _{GS} =-10V, I _D =-10A	---	32	39	mΩ
		V _{GS} =-4.5V, I _D =-10A	---	46	62	
g _f s	Forward Transconductance	V _{DS} =-5V, I _D =-6A	---	13	---	S
Dynamic Characteristics^⑤						
C _{iss}	Input Capacitance	V _{GS} =0V, V _{DS} =-20V, Freq.=1MHz	---	668	---	pF
C _{oss}	Output Capacitance		---	98	---	
C _{rss}	Reverse Transfer Capacitance		---	72	---	
T _{d(on)}	Turn-on Delay Time	V _{DD} =-20V , V _{GS} =-10V , R _G =6Ω, I _D =-1A	---	8.7	---	nS
T _r	Turn-on Rise Time		---	7	---	
T _{d(off)}	Turn-off Delay Time		---	31	---	
T _f	Turn-off Fall Time		---	17	---	
Q _g	Total Gate Charge	V _{DS} =-20V , V _{GS} =-10V, I _D =-10A	---	15	---	nC
Q _{gs}	Gate-Source Charge		---	2.4	---	
Q _{gd}	Gate-Drain Charge		---	3.5	---	
Source-Drain Characteristics						
V _{SD} ^④	Diode Forward Voltage	V _{GS} =0V, I _S =-1A , T _J =25°C	---	---	-1	V
I _S	Continuous Source Current	V _G =V _D =0V , Force Current	---	---	-6	A
I _{SM}	Pulsed Source Current		---	---	-22	A

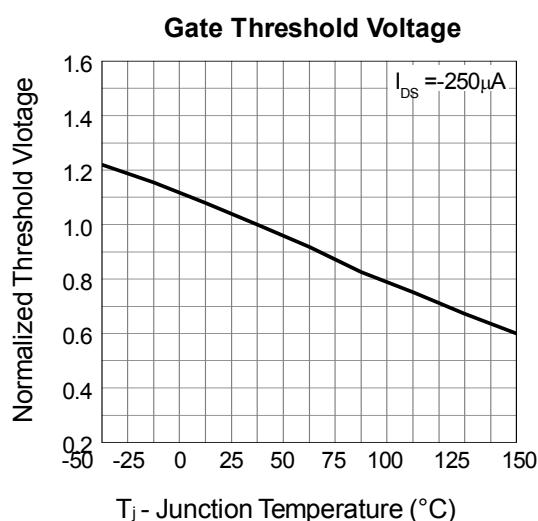
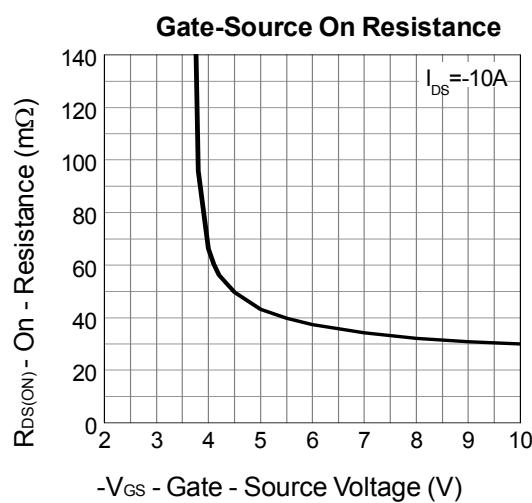
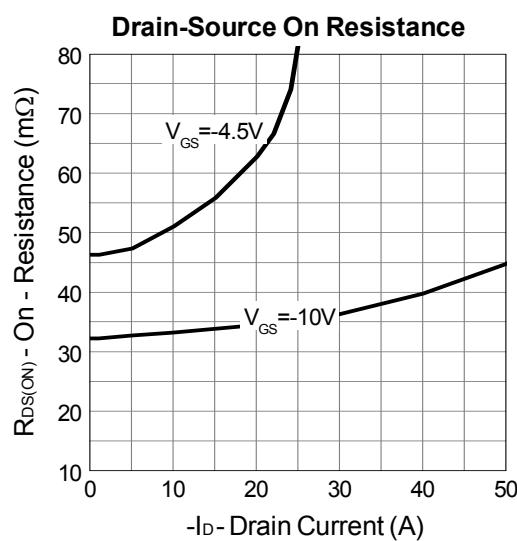
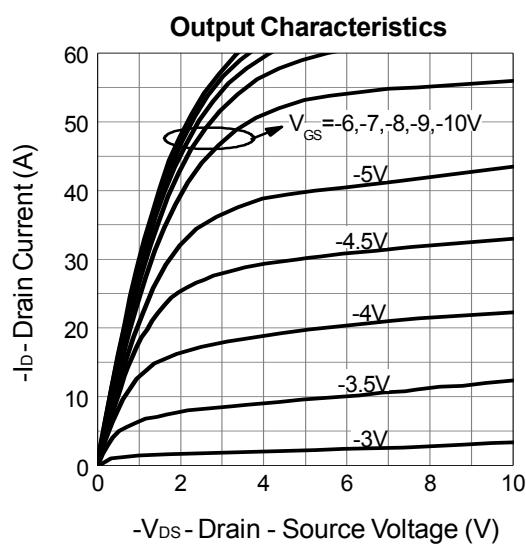
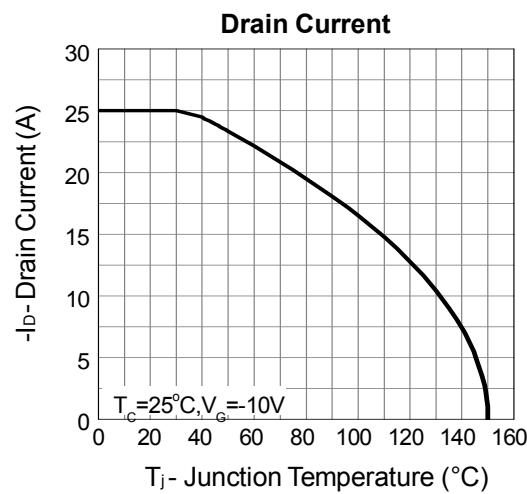
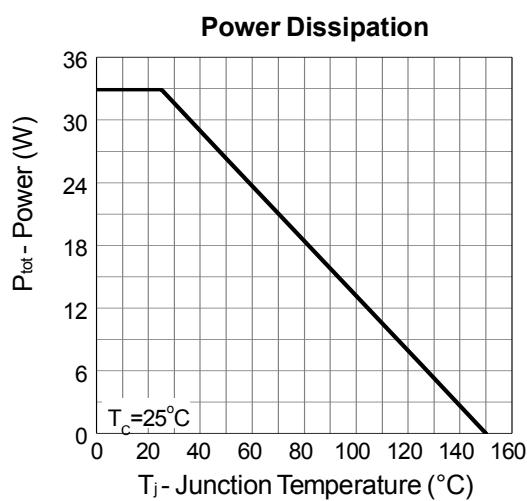
Note ④: Pulse test (pulse width 300us, duty cycle 2%).

Note ⑤ : Guaranteed by design, not subject to production testing.

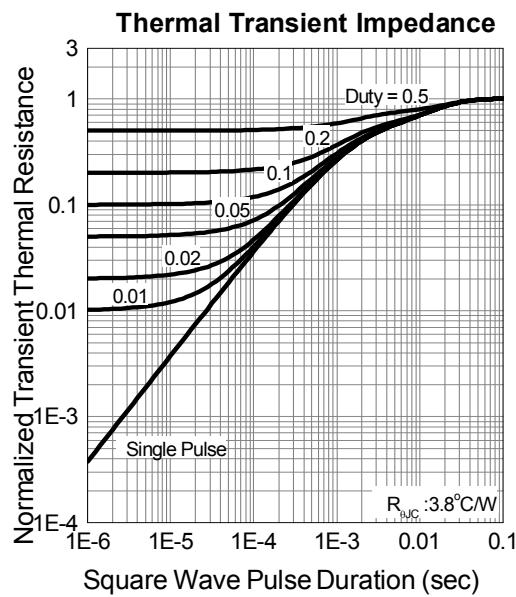
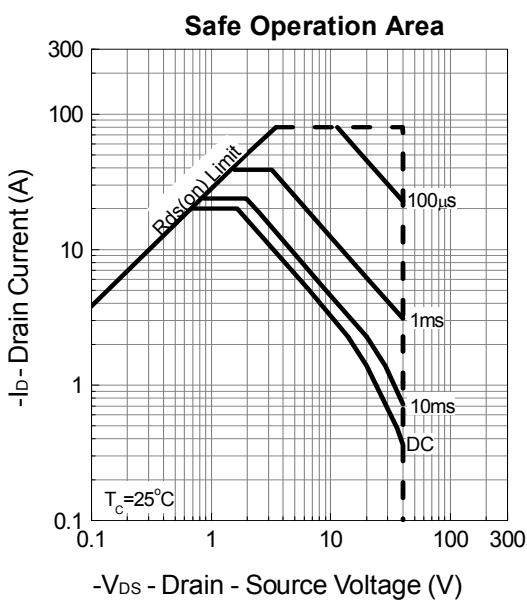
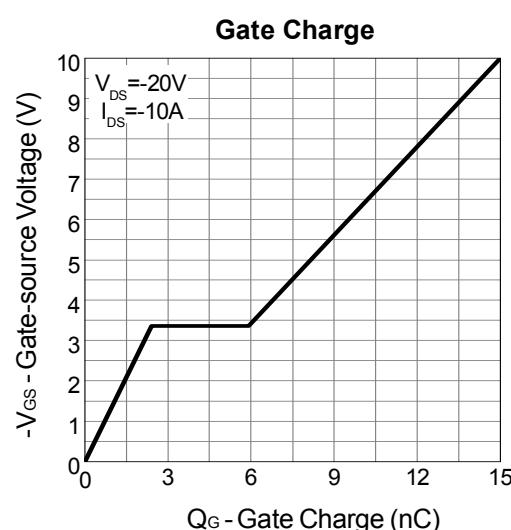
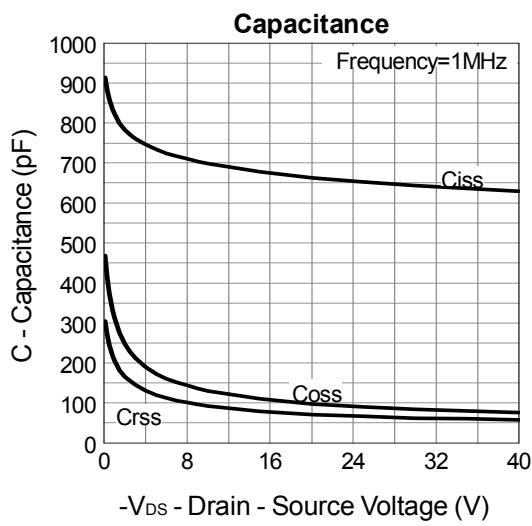
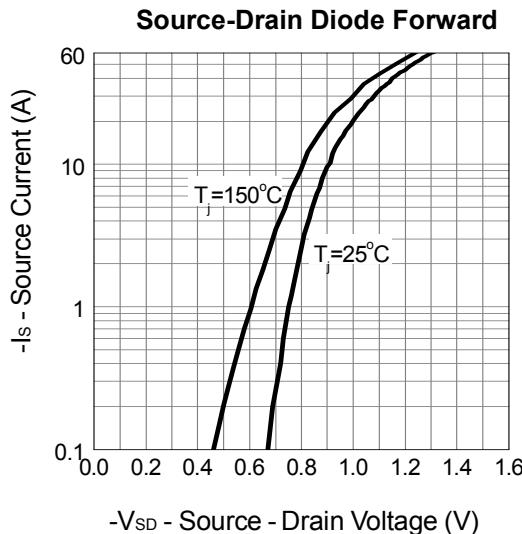
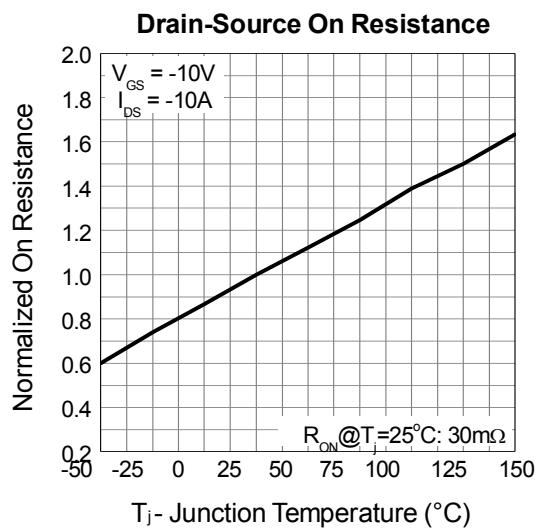
Dual N+P Channel Enhancement Mode MOSFET
N Channel Typical Operating Characteristics


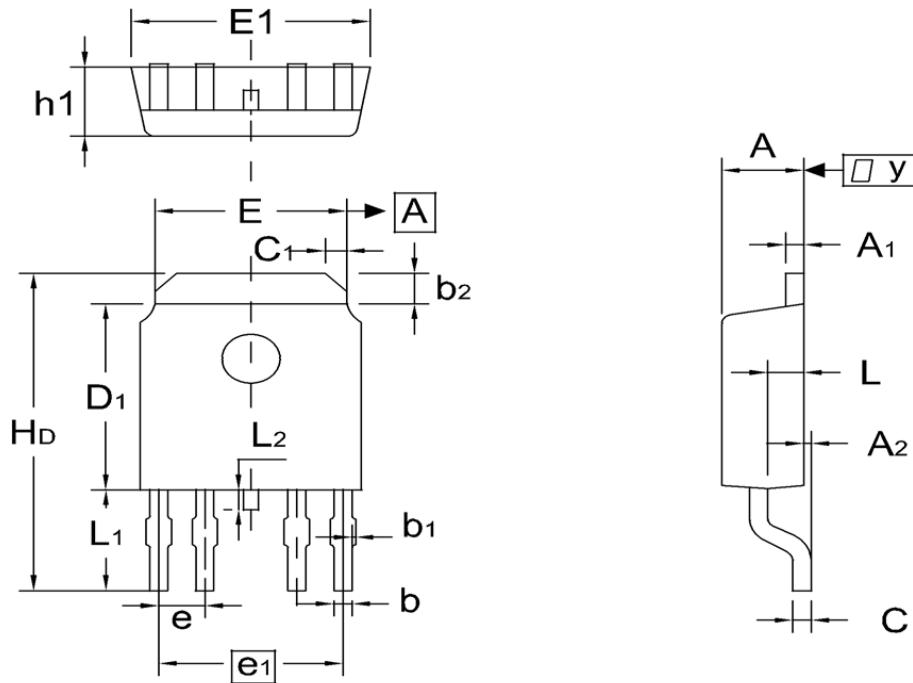
Dual N+P Channel Enhancement Mode MOSFET



Dual N+P Channel Enhancement Mode MOSFET
P Channel Typical Operating Characteristics


Dual N+P Channel Enhancement Mode MOSFET



Dual N+P Channel Enhancement Mode MOSFET
TO-252-4L Package Outline Dimensions

DIMENSIONS (unit : mm)

Symbol	Min	Typ	Max	Symbol	Min	Typ	Max
A	2.1	2.3	2.5	A ₁	0.4	0.5	0.6
A ₂	--	--	0.3	b	0.4	0.5	0.6
b ₁	--	--	0.1	b ₂	0.8	1.0	1.2
C	0.4	0.5	0.6	C ₁	0.4	0.6	0.8
D ₁	5.7	6.1	6.5	E	5.0	5.3	5.6
E ₁	6.3	6.6	6.9	e	--	1.27	--
e ₁	--	5.08	--	H _D	9.6	10.0	10.4
h ₁	2.1	2.3	2.5	L	0.80	1.0	1.2
L ₁	2.6	2.9	3.2	L ₂	0.35	0.65	0.95